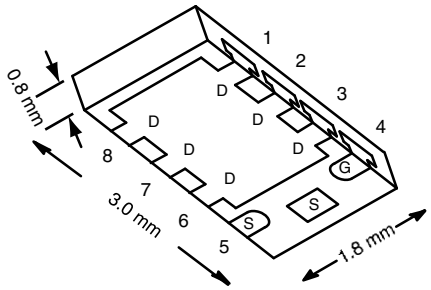
P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I_D (A)	Q_g (Typ.)
- 30	0.015 at V_{GS} = - 10 V	- 12[a]	20 nC
	0.022 at V_{GS} = - 4.5 V	- 12[a]	

PowerPAK® ChipFET® Single



Bottom View

Ordering Information:
Si5429DU-T1-GE3 (Lead (Pb)-free and Halogen-free)

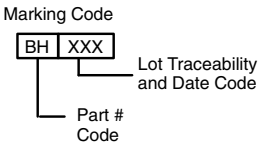
FEATURES

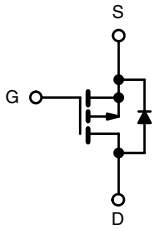
- TrenchFET® Power MOSFET
- Thermally Enhanced PowerPAK® ChipFET® Package
  - Small Footprint Area, Thin 0.8 mm Profile
  - Low On-Resistance
- 100 % R_g Tested
- Material categorization:
  For definitions of compliance please see www.vishay.com/doc?99912

Pb-free
RoHS COMPLIANT
HALOGEN FREE

APPLICATIONS

- Power Management for Mobile Computing
  - Adaptor Switch
  - Load Switch
  - DC/DC Converter





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)				
Parameter		**Symbol**	**Limit**	**Unit**
Drain-Source Voltage		V_{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	- 12[a]	A
	T_C = 70 °C		- 12[a]	
	T_A = 25 °C		- 11.8[b, c]	
	T_A = 70 °C		- 9.4[b, c]	
Pulsed Drain Current (t = 300 µs)		I_{DM}	- 50	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	- 12[a]	
	T_A = 25 °C		- 11.86[b, c]	
Maximum Power Dissipation	T_C = 25 °C	P_D	31	W
	T_C = 70 °C		20	
	T_A = 25 °C		3.1[b, c]	
	T_A = 70 °C		2[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature)[d, e]			260	

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Maximum Junction-to-Ambient[b, f]	t ≤ 5 s	R_{thJA}	34	40	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	3	4	

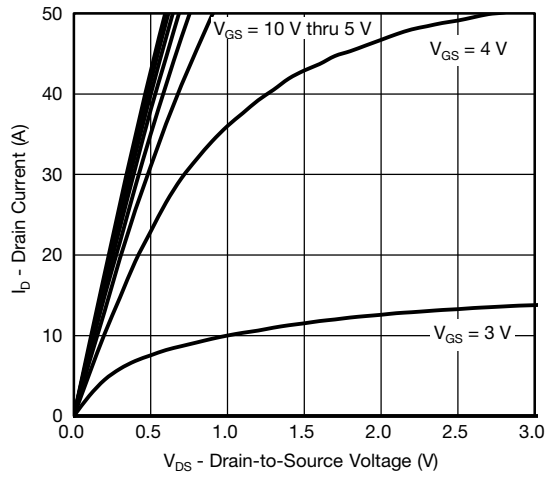
Notes:
a. Package limited.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. See solder profile (www.vishay.com/doc?73257). The PowerPAK ChipFET is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
f. Maximum under steady state conditions is 90 °C/W.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = - 250 µA	- 30			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = - 250 µA		- 20		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			4.4		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D = - 250 µA	- 1.0		- 2.2	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = - 30 V, V_{GS} = 0 V			- 1	µA
		V_{DS} = - 30 V, V_{GS} = 0 V, T_J = 55 °C			- 5	
		V_{DS} = - 3 V, V_{GS} = 0 V		- 0.0001		
		V_{DS} = - 3 V, V_{GS} = 0 V, T_J = 0 °C		- 0.0001		
		V_{DS} = - 3 V, V_{GS} = 0 V, T_J = 55 °C		- 0.0001		
On-State Drain Current[a]	$I_{D(on)}$	$V_{DS} \leq$ - 5 V, V_{GS} = - 4.5 V	- 20			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = - 10 V, I_D = - 7 A		0.0122	0.015	Ω
		V_{GS} = - 4.5 V, I_D = - 5 A		0.0178	0.022	
Forward Transconductance[a]	g_{fs}	V_{DS} = - 10 V, I_D = - 7 A		25		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = - 15 V, V_{GS} = 0 V, f = 1 MHz		2320		pF
Output Capacitance	C_{oss}			275		
Reverse Transfer Capacitance	C_{rss}			235		
Total Gate Charge	Q_g	V_{DS} = - 15 V, V_{GS} = - 10 V, I_D = - 12 A		42	63	nC
		V_{DS} = - 15 V, V_{GS} = - 4.5 V, I_D = - 12 A		20	30	
Gate-Source Charge	Q_{gs}			6.3		
Gate-Drain Charge	Q_{gd}			6.3		
Gate Resistance	R_g	f = 1 MHz	0.8	4.2	8.4	Ω
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = - 15 V, R_L = 1.5 Ω $I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		35	70	ns
Rise Time	t_r			25	50	
Turn-Off Delay Time	$t_{d(off)}$			31	60	
Fall Time	t_f			10	20	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = - 15 V, R_L = 1.5 Ω $I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		10	20	
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(off)}$			40	80	
Fall Time	t_f			10	20	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			- 12	A
Pulse Diode Forward Current	I_{SM}				50	
Body Diode Voltage	V_{SD}	I_S = - 10 A, V_{GS} = 0 V		- 0.83	- 1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = - 10 A, dI/dt = 100 A/µs, T_J = 25 °C		10	20	ns
Body Diode Reverse Recovery Charge	Q_{rr}			3	10	nC
Reverse Recovery Fall Time	t_a			6		ns
Reverse Recovery Rise Time	t_b			4		

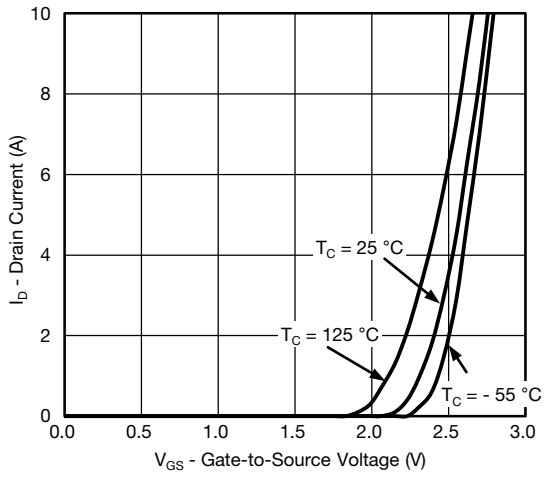
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %
a. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

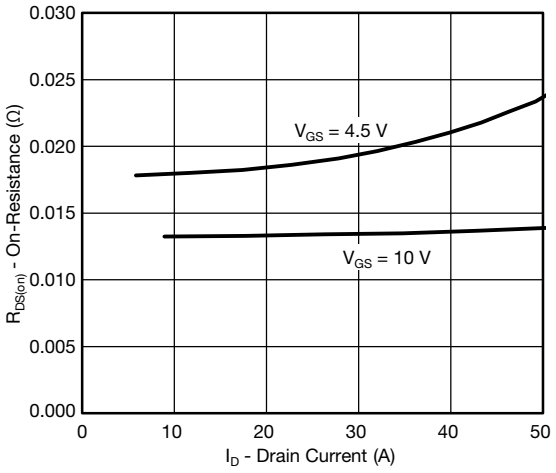
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



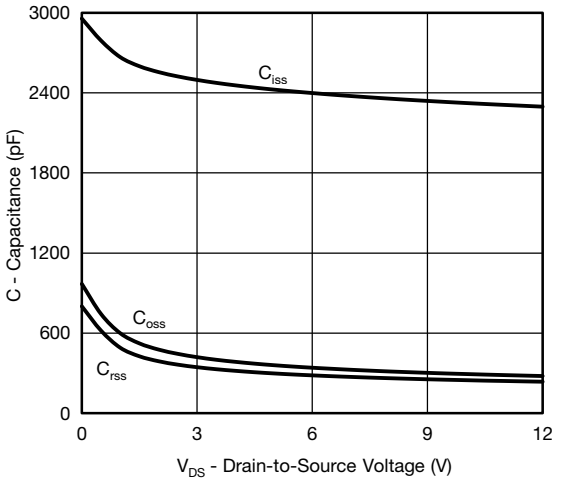
Output Characteristics



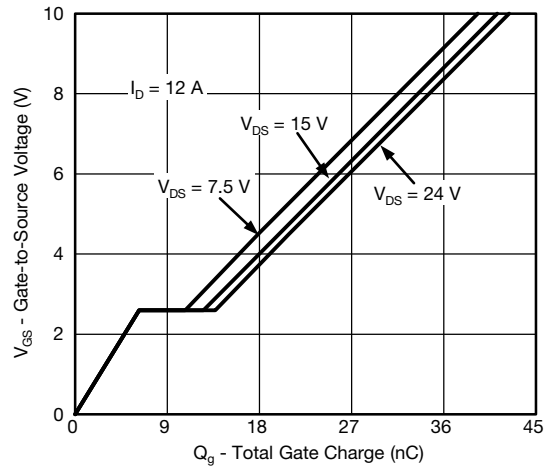
Transfer Characteristics



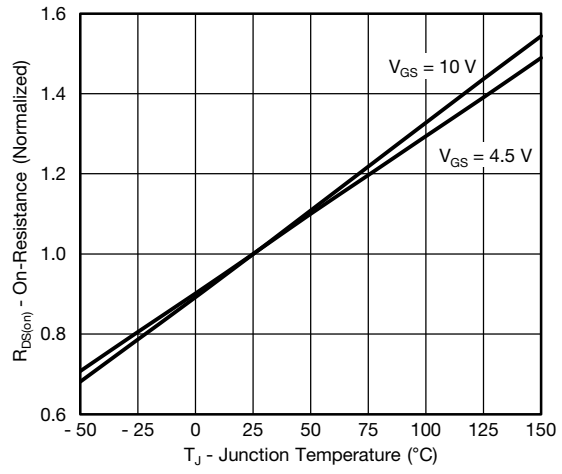
On-Resistance vs. Drain Current



Capacitance

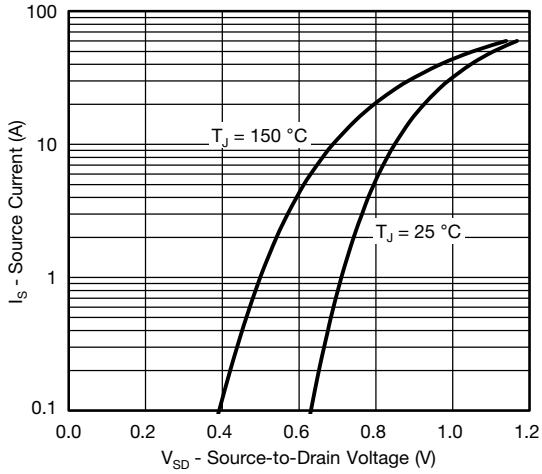


Gate Charge

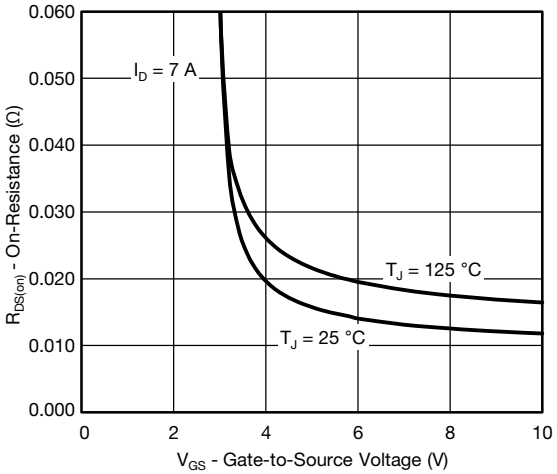


On-Resistance vs. Junction Temperature

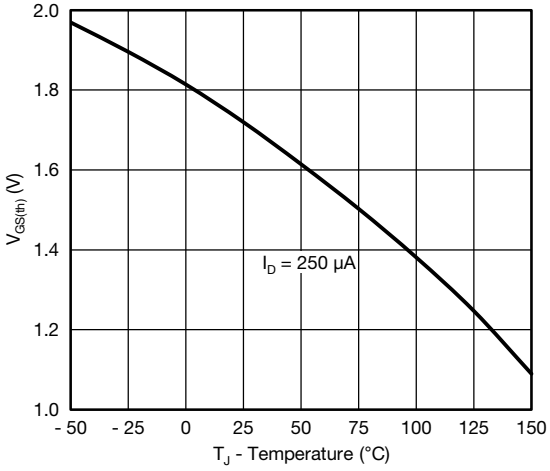
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



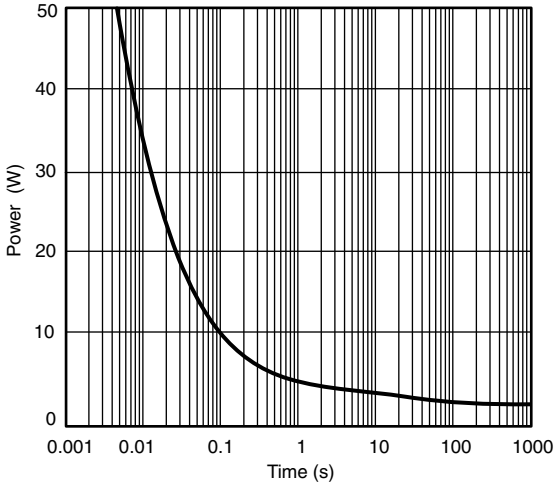
Source-Drain Diode Forward Voltage



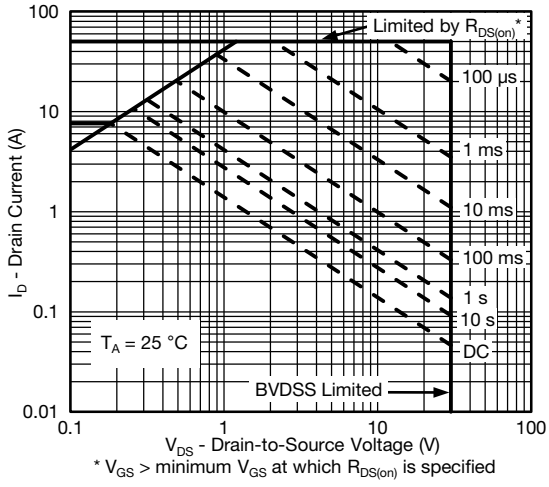
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power

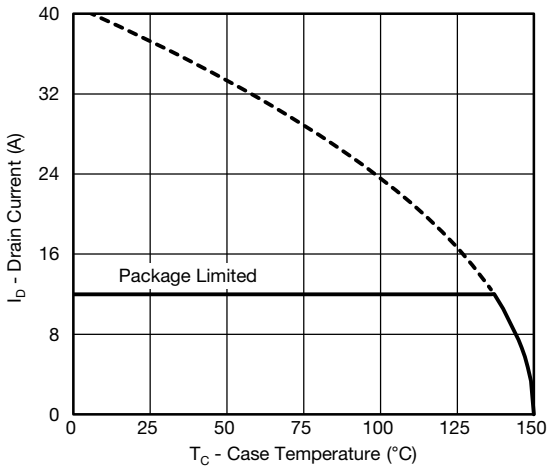


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

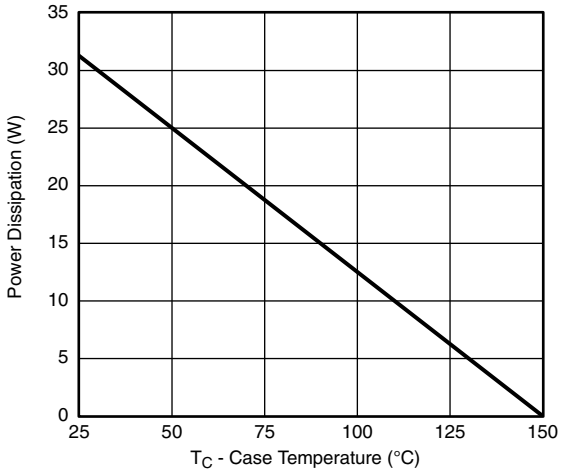
Safe Operating Area

For technical support, please contact: pmostechsupport@vishay.com
Document Number: 63933
S12-0804-Rev. A, 16-Apr-12

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



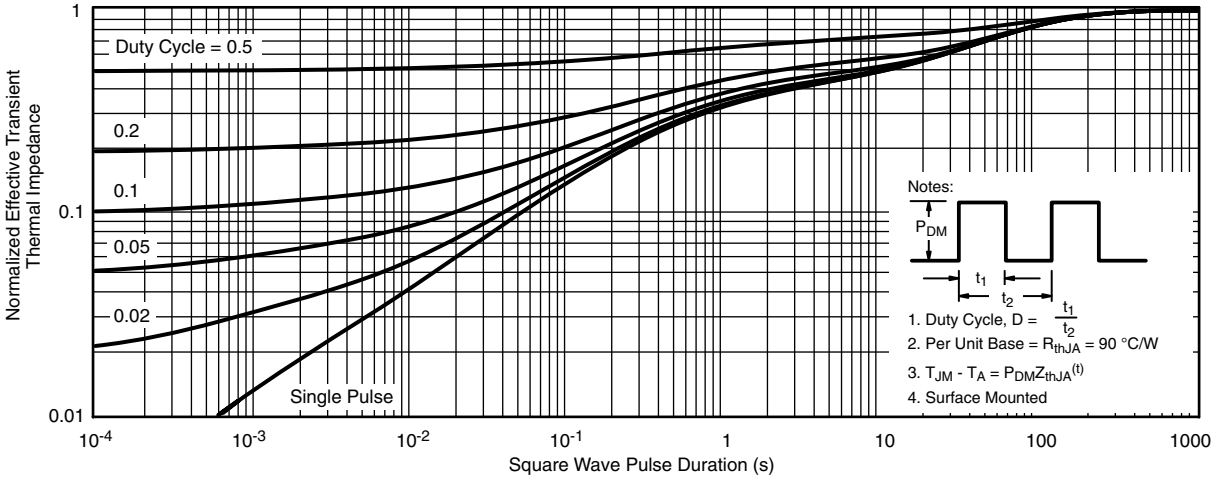
Current Derating*



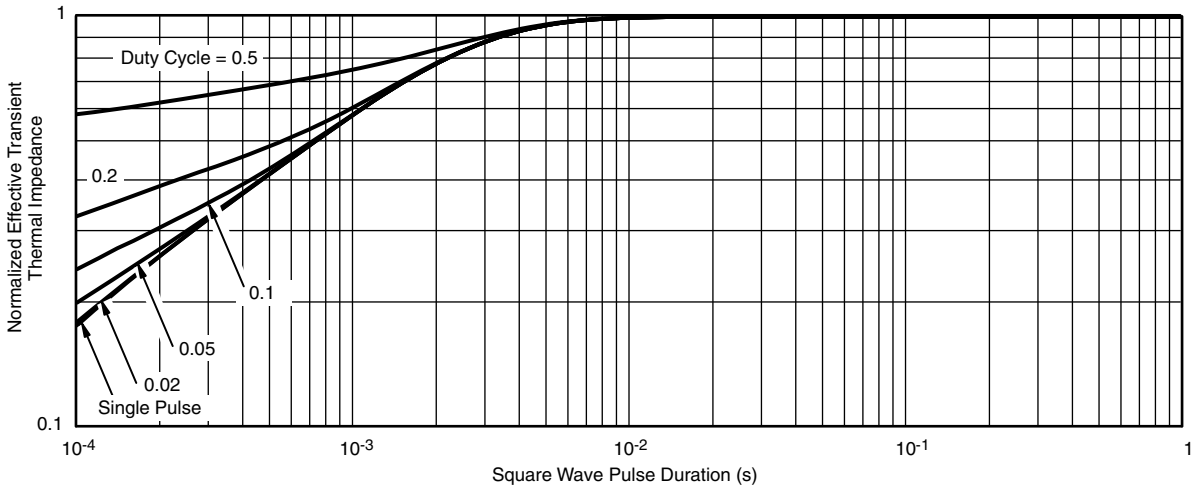
Power Derating

* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



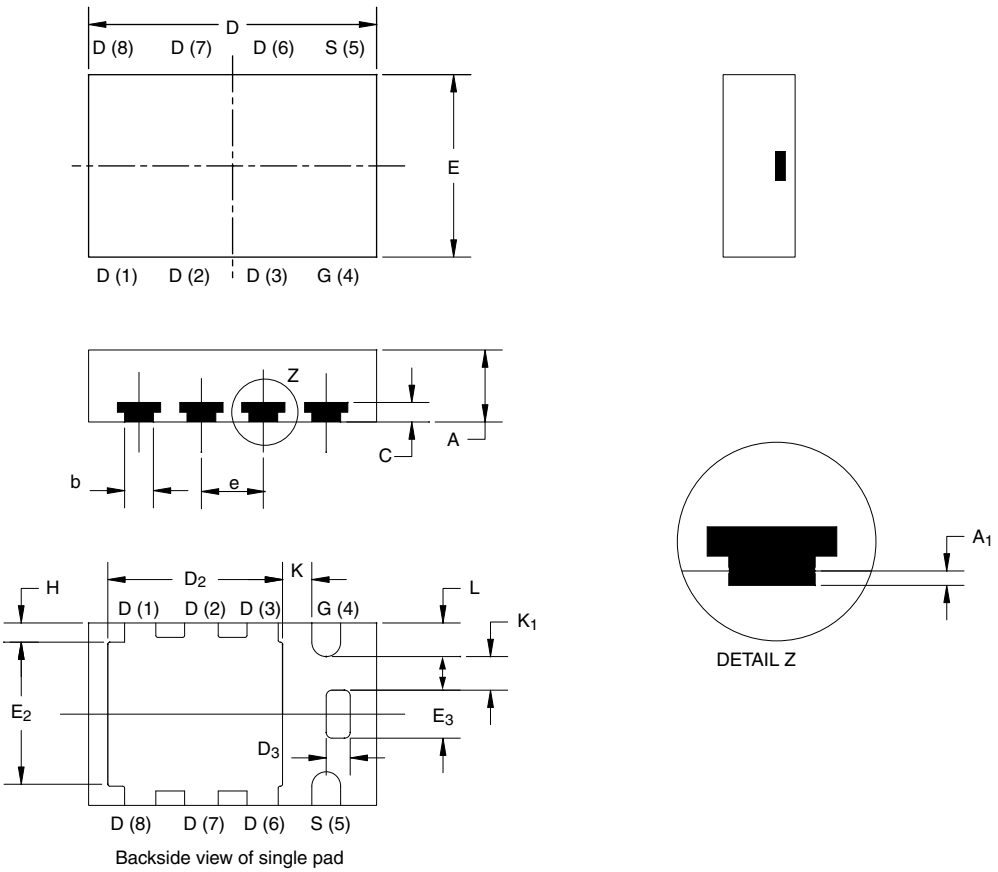
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63933.

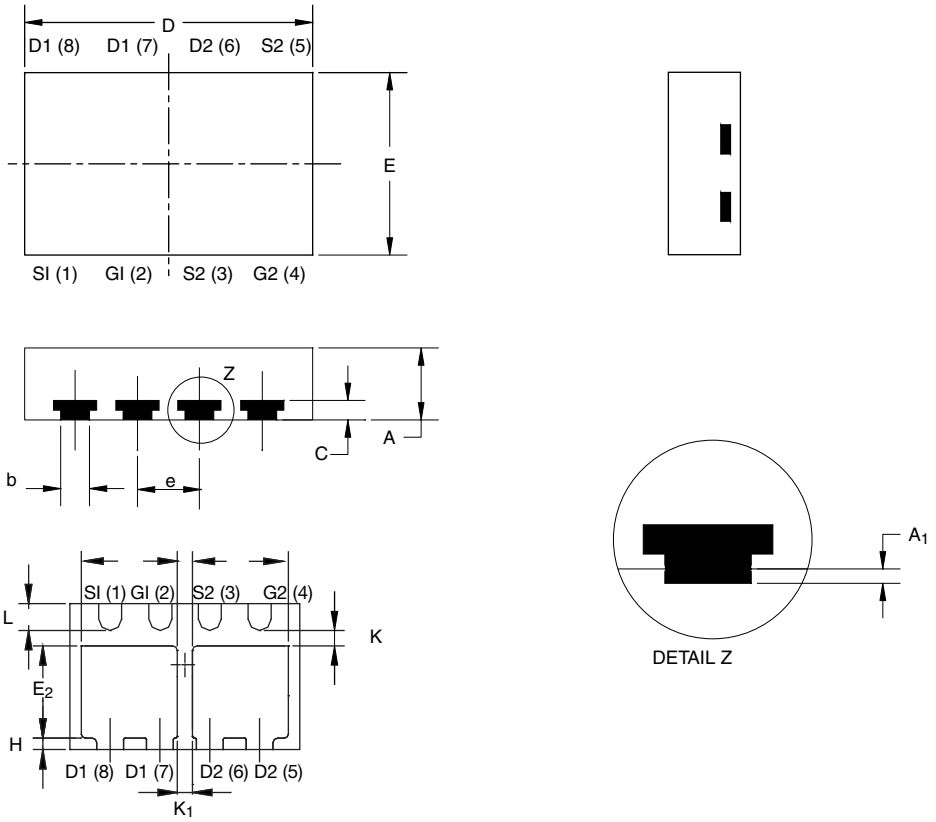
PowerPAK® ChipFET® SINGLE PAD



Backside view of single pad

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.85	0.028	0.030	0.033
A_1	0	-	0.05	0	-	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
C	0.15	0.20	0.25	0.006	0.008	0.010
D	2.92	3.00	3.08	0.115	0.118	0.121
D_2	1.75	1.87	2.00	0.069	0.074	0.079
D_3	0.20	0.25	0.30	0.008	0.010	0.012
E	1.82	1.90	1.98	0.072	0.075	0.078
E_2	1.38	1.50	1.63	0.054	0.059	0.064
E_3	0.45	0.50	0.55	0.018	0.020	0.022
e	0.65 BSC			0.026 BSC		
H	0.15	0.20	0.25	0.006	0.008	0.010
K	0.25	-	-	0.010	-	-
K_1	0.30	-	-	0.012	-	-
L	0.30	0.35	0.40	0.012	0.014	0.016

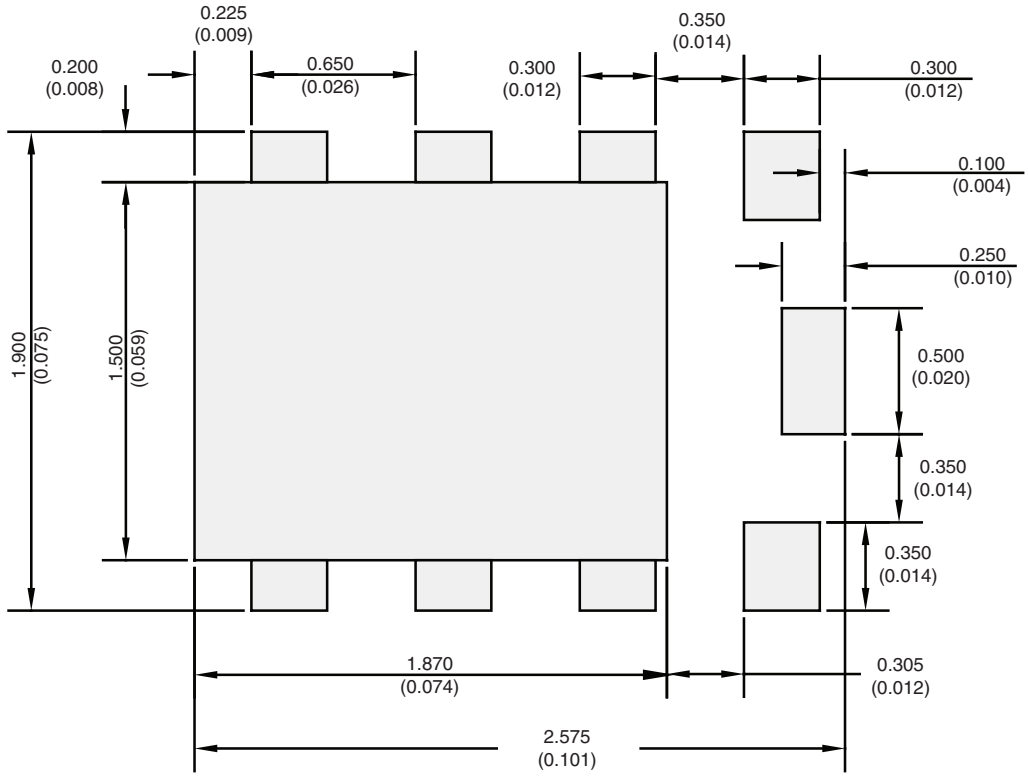
PowerPAK® ChipFET® DUAL PAD



Backside view of dual pad

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.85	0.028	0.030	0.033
A_1	0	-	0.05	0	-	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
C	0.15	0.20	0.25	0.006	0.008	0.010
D	2.92	3.00	3.08	0.115	0.118	0.121
D_2	1.07	1.20	1.32	0.042	0.047	0.052
E	1.82	1.90	1.98	0.072	0.075	0.078
E_2	0.92	1.05	1.17	0.036	0.041	0.046
e	0.65 BSC			0.026 BSC		
H	0.15	0.20	0.25	0.006	0.008	0.010
K	0.20	-	-	0.008	-	-
K_1	0.20	-	-	0.008	-	-
L	0.30	0.35	0.40	0.012	0.014	0.016
ECN: C10-0618-Rev. C, 19-Jul-09 DWG: 5940						

RECOMMENDED MINIMUM PADS FOR PowerPAK® ChipFET® Single



Recommended Minimum Pads
Dimensions in mm/(Inches)

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